

WITHDRAWAL OF ADOPTION NOTICE

The Department of Defense has determined it no longer has an interest in IPC-TM-650 number 2.5.5.2, "Dielectric Constant and Dissipation Factor of Printed Wiring Board Material-Clip Method", and is hereby withdrawing its adoption of this document as of 27 November 2008.

Custodians:
Army – CR
Navy – EC
Air Force – 85

Preparing activity:
DLA – CC

Project: 5998-2009-009

Review activities:
Army – MI
Air Force – 99

NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at <http://assist.daps.dla.mil>.